SCBS186A - FEBRUARY 1991 - REVISED JULY 1994

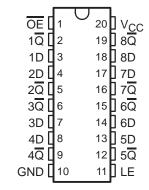
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V_{OLP} (Output Ground Bounce) < 1 V at $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$
- High-Drive Outputs (-32-mA I_{OH}, 64-mA IOI)
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

description

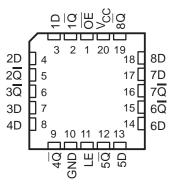
The 'ABT533 are 8-bit transparent D-type latches with 3-state outputs designed specifically for driving highly capacitive or relatively lowimpedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

When the latch-enable (LE) input is high, the Q outputs follow the complements of the data (D) inputs. When LE is taken low, the Q outputs are latched at the inverse of the levels set up at the D inputs. The 'ABT533 provides inverted data at its outputs.

SN54ABT533 . . . J PACKAGE SN74ABT533 . . . DB. DW. OR N PACKAGE (TOP VIEW)



SN54ABT533 . . . FK PACKAGE (TOP VIEW)



A buffered output-enable (\overline{OE}) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Previously stored data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down, $\overline{\sf OE}$ should be tied to ${\sf V}_{\sf CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT533 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT533 is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ABT533 is characterized for operation from -40°C to 85°C.

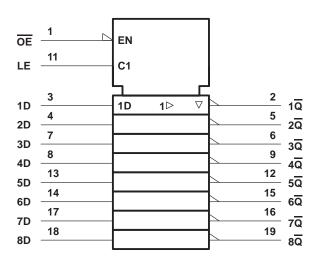
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2-1

FUNCTION TABLE (each latch)

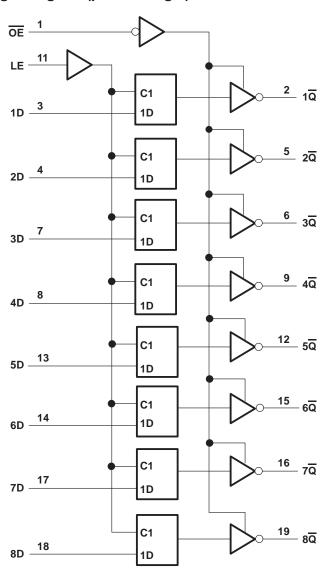
	INPUTS		ОИТРИТ
OE	LE	D	Q
L	Н	Н	L
L	Н	L	Н
L	L	Χ	\overline{Q}_0
Н	X	Χ	Z

logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC} –0.5 V to 7 V
Input voltage range, V _I (see Note 1)
Voltage range applied to any output in the high state or power-off state, V _O −0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT533
SN74ABT533 128 mA
Input clamp current, I_{IK} ($V_I < 0$)
Output clamp current, I_{OK} ($V_O < 0$)
Maximum power dissipation at T _A = 55°C (in still air) (see Note 2): DB package 0.6 W
DW package 1.6 W
N package 1.3 W
Storage temperature range

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.

recommended operating conditions (see Note 3)

		SN54ABT533		SN74ABT533		UNIT
		MIN	MAX	MIN	MAX	UNII
Vcc	Supply voltage	4.5	5.5	4.5	5.5	V
VIH	High-level input voltage	2	EN	2		V
V_{IL}	Low-level input voltage		0.8		0.8	V
٧ _I	Input voltage	0 <	Vcc	0	Vcc	V
IOH	High-level output current	(5)	-24		-32	mA
loL	Low-level output current	700	48		64	mA
Δt /Δν	Input transition rise or fall rate	A)	10		10	ns/V
TA	Operating free-air temperature	-55	125	-40	85	°C

NOTE 3: Unused or floating inputs must be held high or low.

SN54ABT533, SN74ABT533 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS		Т	A = 25°C	;	SN54ABT533		SN74ABT533		UNIT	
PARAMETER	TEST CONDITIONS			MIN	TYP†	MAX	MIN	MAX	MIN	MAX	UNII
VIK	$V_{CC} = 4.5 \text{ V},$	I _I = -18 mA				-1.2		-1.2		-1.2	V
	V _{CC} = 4.5 V, I _{OH} = -3 mA						2.5		2.5		
V	$V_{CC} = 5 \text{ V}, \qquad I_{OH} = -3 \text{ mA}$		3			3		3		V	
VOH	V _{CC} = 4.5 V	I _{OH} = -24 mA		2			2				V
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$		2*					2		
Va	V _{CC} = 4.5 V					0.55		0.55			V
VOL						0.55*				0.55	V
lį	$V_{CC} = 5.5 V,$	$C = 5.5 \text{ V}, V_I = V_{CC} \text{ or GND}$				±1		± 1		±1	μΑ
lozh	$V_{CC} = 5.5 \text{ V}, V_{O} = 2.7 \text{ V}$					10‡		2 10‡		10‡	μΑ
lozL	$V_{CC} = 5.5 \text{ V}, V_{O} = 0.5 \text{ V}$					-10‡		-10‡		-10‡	μΑ
I _{off}	$V_{CC} = 0$, $V_I \text{ or } V_O \le 4.5 \text{ V}$				±150	S			±150	μΑ	
ICEX	$V_{CC} = 5.5 V$,	V _O = 5.5 V	Outputs high			50	90	50		50	μΑ
ΙΟ [§]	$V_{CC} = 5.5 V$,	V _O = 2.5 V	_	-50	-140	-180	-50	-180	-50	-180	mA
			Outputs high		1	250		250		250	μΑ
ICC	$V_{CC} = 5.5 \text{ V},$ $V_{I} = V_{CC} \text{ or } G$		Outputs low		24	30		30		30	mA
		ND	Outputs disabled		0.5	250		250		250	μΑ
	V _{CC} = 5.5 V,		Outputs enabled			1.5		1.5		1.5	
ΔI_{CC}	One input at 3.4 V, Other inputs at V _{CC} or GND		Outputs disabled			1.5		1.5		1.5	mA
			Control inputs			1.5		1.5		1.5	
Ci	V _I = 2.5 V or 0.5 V				3						pF
Co	$V_0 = 2.5 \text{ V or } 0$	0.5 V			9						pF

^{*} On products compliant to MIL-STD-883, Class B, this parameter does not apply.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			V _{CC} =	V _{CC} = 5 V, T _A = 25°C		ВТ533	SN74AI	UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	
t _W	Pulse duration, LE high		3.3		3.3	10,71	3.3		ns
t _{su}	Setup time, data before LE↓	High or low	2.1		2.1	110	2.1		ns
t _h	Hold time, data after LE \downarrow	High or low	1.5§		1.5§		1.5§		ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$.

[‡] This data sheet limit may vary among suppliers.

[§] Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

 $[\]P$ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

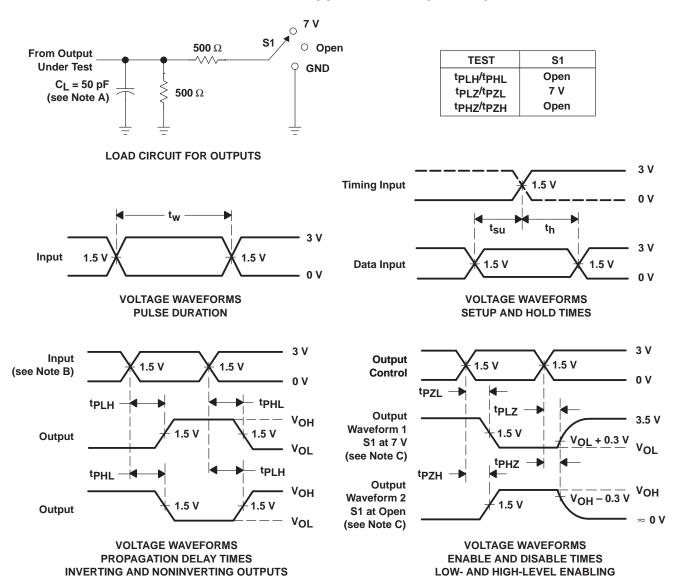
SN54ABT533, SN74ABT533 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM TO (INPUT) (OUTPUT)		V _{CC} = 5 V, T _A = 25°C		SN54ABT533		SN74ABT533		UNIT	
	(INPOT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	D	Q	1.9	4.2	5.4	1.9	6.7	1.9	6.4	20
^t PHL		Q	3.1	4.9	6.3	3.1	6.9	3.1	6.6	ns
^t PLH		Q	2.7	4.9	6.2	2.7	7.6	2.7	7.3	
^t PHL	LE	Q	3.5	5.4	6.8	3.5 <	7.5	3.5	7.3	ns
^t PZH	ŌĒ	Q	1.6	3.7	4.8	1.6	5.8	1.6	5.7	
^t PZL	OE	Q	2.4	4.2	6.2	2.4	6.9	2.4	6.7	ns
^t PHZ	ŌĒ	Q	2.8	5.1	6.2	2.8	7.2	2.8	6.9	
t _{PLZ}	000	Q	2	4.1	6	2	6.9	2	6.5	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$, $t_f \leq 2.5$ ns. $t_f \leq 2.5$ ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







i.com 26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9584301Q2A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9584301QRA	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
5962-9584301QSA	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC
SN74ABT533DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
SN74ABT533DW	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74ABT533DWR	OBSOLETE	SOIC	DW	20		TBD	Call TI	Call TI
SN74ABT533N	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SNJ54ABT533FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ABT533J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54ABT533W	ACTIVE	CFP	W	20	1	TBD	Call TI	Level-NC-NC-NC

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within Mil-Std 1835 GDFP2-F20



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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